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FXO-HC520-10

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Datasheet of FXO-HC520-10 - OSC XO 10.000MHZ HCMOS SMD

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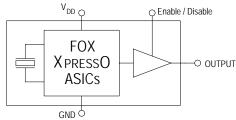
5 x 3.2mm 2.5V Oscillator

Model: FXO-HC52 SERIES

Freq: 0.75 MHz to 180MHz Rev. 03/24/2008

Features

- 0 XTREMELY Low Jitter
- Low Cost
- XPRESS Delivery
- Frequency Resolution to six decimal places
- Stabilities to ± 20 PPM
- -20 to +70°C or -40 to +85°C operating temperatures
- Tri-State Enable / Disable Feature
- Industry Standard Package, Footprint & Pin-Out
- Fully RoHS compliant
- Gold over Nickel Termination Finish
- Serial ID with Comprehensive Traceability



For more information -- Click on the drawing





page

Applications

- ANY application requiring an oscillator
- SONET
- Ethernet
- Storage Area Network
- **Broadband Access**
- Microprocessors / DSP / FPGA
- **Industrial Controllers**
- Test and Measurement Equipment
- Fiber Channel

Description

The Fox XPRESSO Crystal Oscillator is a breakthrough in configurable Frequency Control Solutions. XPRESSO utilizes a family of proprietary ASICs, designed and developed by Fox, with a key focus on noise reduction technologies.

The 3rd order Delta Sigma Modulator reduces noise to the levels that are comparable to traditional Bulk Quartz and SAW oscillators. The ASICs family has ability to select the output type, input voltages, and temperature performance features.

With the XPRESS lead-time, low cost, low noise, wide frequency range, excellent ambient performance, XpressO is an excellent choice over the conventional technologies.

Contents

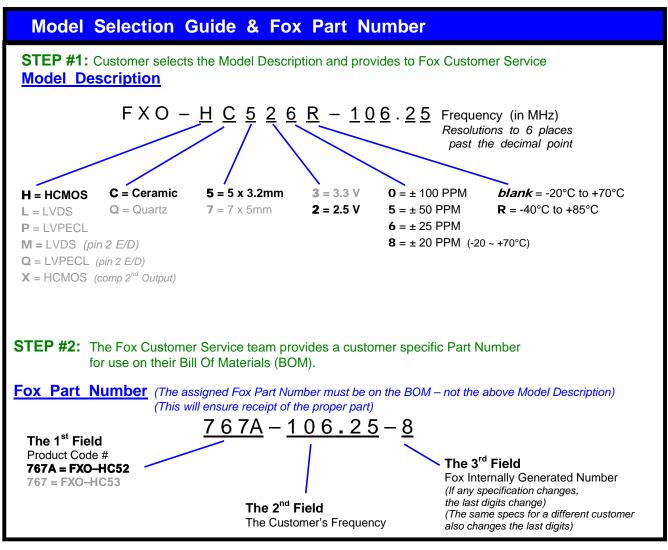
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Finished XPRESSO parts are 100% final tested.

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This example, FXO-HC526R-106.25 = HCMOS Output, Ceramic 5 x 3.2mm Package, 2.5V, ±25 PPM Stability, -40 to +85°C Temperature Range, at 106.25 MHz









Electrical Characteristics				
Parameters	Symbol	Condition	Maximum Value (unless otherwise noted)	
Frequency Range	Fo		0.750 to 180.000 MHz	
Frequency Stability 1			100, 50, 25, & 20 ppm	
Temperature Range	T _O	Standard operating Optional operating Storage	-20°C to +70°C -40°C to +85°C -55°C to +125°C	
Supply Voltage	V_{DD}	Standard	2.5 V ± 5%	
Input Current (@ 15pF LOAD)	I _{DD}	0.75 ~ 20 MHz 20+ ~ 50 MHz 50+ ~ 100 MHz 100+ ~ 130 MHz 130+ ~ 160 MHz 160+ ~ 180 MHz	22 mA 25 mA 29 mA 32 mA 35 mA 37 mA	
Output Load	HCMOS	Standard	15 pF	
Start-Up Time	Ts		10 mS	
Output Enable / Disable Time			100 nS	
Moisture Sensitivity Level	MSL	JEDEC J-STD-20	1	
Termination Finish			Au	

Note 1 – Stability is inclusive of 25°C tolerance, operating temperature range, input voltage change, load change, aging, shock and vibration.

Absolute	Maximum	Ratings

(Useful life may be impaired. For user guidelines only, not tested)

Operation is only guaranteed for voltage and temperature specifications in Electrical Characteristics section.)

Parameters	Symbol	Condition	Maximum Value (unless otherwise noted)
Input Voltage	V_{DD}		-0.5V to +5.0V
Operating Temperature	T _{AMAX}		–55°C to +105°C
Storage Temperature	T _{STG}		–55°C to +125°C
Junction Temperature			125°C
ESD Sensitivity	HBM	Human Body Model	> 1 kV

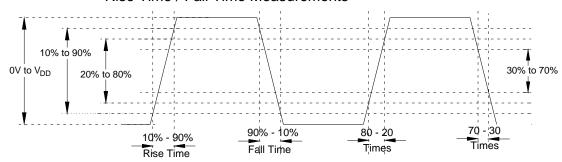


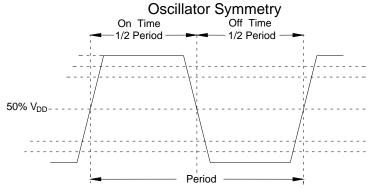


Output Wave Characteristics				
Parameters	Symbol	Condition	Maximum Value (unless otherwise noted)	
Output LOW Voltage	V _{OL}	0.75 to 160 MHz 160+ to 180 MHz	10% V _{DD} 20% V _{DD}	
Output HIGH Voltage	V _{OH}	0.75 to 160 MHz 160+ to 180 MHz	90% V _{DD} MIN 80% V _{DD} MIN	
Output Symmetry (See Drawing Below)		@ 50% V _{DD} Level	45% ~ 55%	
Output Enable (PIN # 1) Voltage	V _{IH}		≥ 70% V _{DD}	
Output Disable (PIN#1) Voltage	V _{IL}		≤ 30% V _{DD}	
Cycle Rise Time (See Drawing Below)	T _R	0.75 to 160 MHz 160+ to 180 MHz	3.5 nS _(10%-90%) 2.5 nS _(20%-80%)	
Cycle Fall Time (See Drawing Below)	T _F	0.75 to 160 MHz 160+ to 180 MHz	3.5 nS _(90%~10%) 2.5 nS _(80%~20%)	

If 30% to 70% times are used, Rise and Fall times change to 2 nS from 0.75 to 180MHz If 20% to 80% times are used, Rise and Fall times change to 2.5 nS from 0.75 to 160MHz

Rise Time / Fall Time Measurements

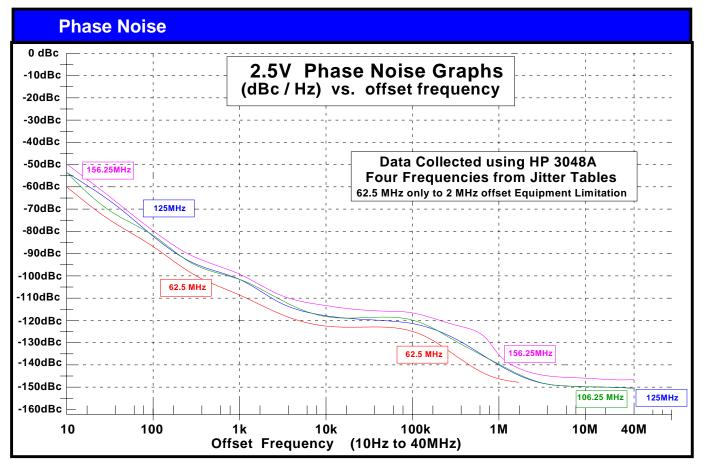




Ideally, Symmetry should be 50/50 -- Other expressions are 45/55 or 55/45







Jitter is frequency dependent. Below are typical values at select frequencies.

Phase Jitter & Time Interval Error (TIE)				
Frequency	Phase Jitter (12kHz to 20MHz)	TIE (Sigma of Jitter Distribution)	Units	
62.5 MHz	2.1	3.1	pS RMS	
106.25 MHz	1.2	3.5	pS RMS	
125 MHz	1.1	2.7	pS RMS	
156.25 MHz	0.8	3.7	pS RMS	

Phase Jitter is integrated from HP3048 Phase Noise Measurement System; measured directly into 50 ohm input; V_{DD} = 2.5V.

TIE was measured on LeCroy LC684 Digital Storage Scope, directly into 50 ohm input, with Amherst M1 software; V_{DD} = 2.5V.

Per MJSQ spec (Methodologies for Jitter and Signal Quality specifications)

Random & Deterministic Jitter Composition					
Frequency Random (Rj) Deterministic (Dj) Total Jitter (Tj) (14 x Rj) + Dj					
62.5 MHz	1.3	8.4	27.6 pS		
106.25 MHz	1.4	8.3	27.7 pS		
125 MHz	1.3	6.7	25.6 pS		
156.25 MHz	1.4	9.7	29.5 pS		

Ri and Di, measured on LeCroy LC684 Digital Storage Scope, directly into 50 ohm input, with Amherst M1 software. Per MJSQ spec (Methodologies for Jitter and Signal Quality specifications)

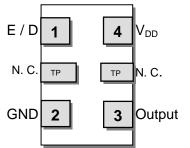




Pin Description and Recommended Circuit					
Pin # Name Type Function		Function			
1	E/D ¹	Logic	Enable / Disable Control of Output (0 = Disabled)		
2	GND	Ground	Electrical Ground for V _{DD}		
3	Output	Output	HCMOS Oscillator Output		
4	V _{DD} 2	Power	Power Supply Source Voltage		
Test Points	N. C.	Hi Z	No Connection (Factory Use ONLY)		

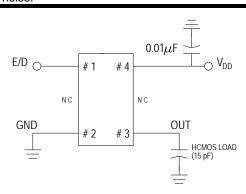
NOTES:

- ¹ Includes pull-up resistor to V_{DD} to provide output when the pin (1) is No Connect.
- Installation should include a $0.01\mu F$ bypass capacitor placed between V_{DD} (Pin 4) and GND (Pin 2) to minimize power supply line noise.

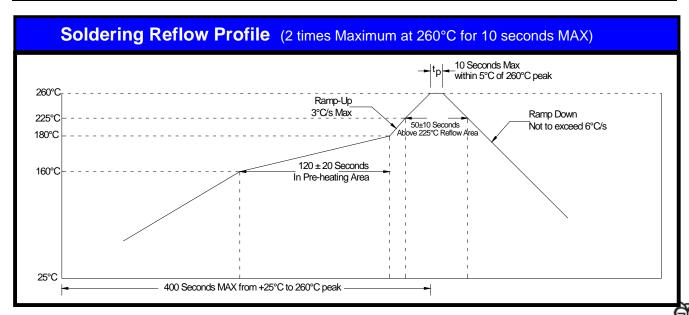


Terminations as viewed from the Top

NOTE: XPRESSO HCMOS XOs are designed to fit on Industry Standard, 4 pad layouts

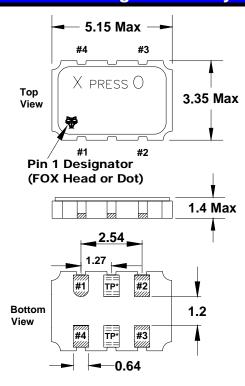


Enable / Disable Control	
Pin # 1 (state)	Output (Pin # 3)
OPEN (No Connection)	ACTIVE Output
"1" Level V _{IH} ≥70% V _{DD}	ACTIVE Output
"0" Level $V_{IL} \le 30\% V_{DD}$	High Impedance





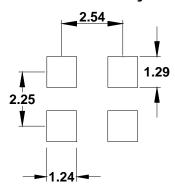
Mechanical Dimensional Drawing & Pad Layout



Actual part marking is depicted.

See **Traceability** (pg. 8) for more information

Recommended Solder Pad Layout



Note: XPRESSO HCMOS XOs are designed to fit on industry standard, 4 pad, layouts.

Pin Connections #1) E/D #3 Output #2 GND #4 VDD *TP are test points and are NC

Drawing is for reference to critical specifications defined by size measurements.

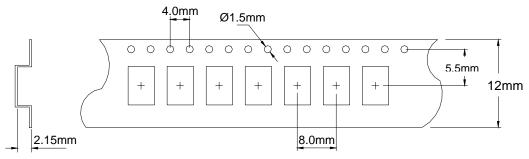
Certain non-critical visual attributes, such as side castellations, reference pin shape, etc. may vary



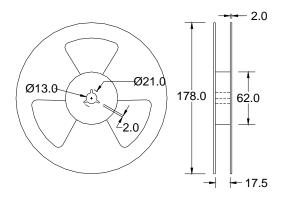




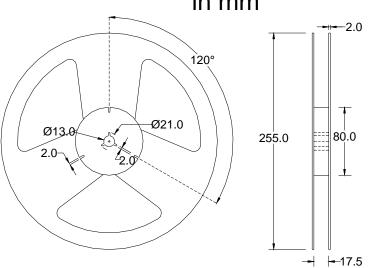
Tape and Reel Dimensions



1k Reel Dimensions in mm



2k Reel Dimensions in mm



Labeling (Reels and smaller packaging are labeled with the below)



An additional identification code is contained internally if tracking should ever be necessary









Traceability - LOT Number & Serial Identification

LOT Number

The LOT Number has direct ties to the customer purchase order. The LOT Number is marked on the "Reel" label, and also stored internally on non-volatile memory inside the XPRESSO part. XPRESSO parts that are shipped Tape and Reel, are also placed in an Electro Static Discharge (ESD) bag and will have the LOT Number labeled on the exterior of the ESD bag.

It is recommended that the XPRESSO parts remain in this ESD bag during storage for protection and identification.

If the parts become separated from the label showing the LOT Number, it can be retrieved from inside one of the parts, and the information that can be obtained is listed below:

- Customer Purchase Order Number
- Internal Fox Sales Order Number
- Dates that the XPRESSO part was shipped from the factory
- The assigned customer part number
- · The specification that the part was designed for

Serial Identification

The Serial ID is the individualized information about the configuration of that particular XPRESSO part. The Serial ID is unique for each and every XPRESSO part, and can be read by special Fox equipment.

With the Serial ID, the below information can be obtained about that individual, XPRESSO part:

- Equipment that the XPRESSO part was configured on
- Raw material used to configure the XPRESSO part
- Traceability of the raw material back to the foundries manufacturing lot
- Date and Time that the part was configured
- Any optimized electrical parameters based on customer specifications
- Electrical testing of the actual completed part
- Human resource that was monitoring the configuration of the part

Fox has equipment placed at key Fox locations World Wide to read the Lot Identification and Serial Number of any XPRESSO part produced and can then obtain the information from above within 24 hours









RoHS Material Declaration

TOTAL			61.196	100.00%	
		Silicon (Si)	0.000125	0.000204%	7440-21-3
	Adhesive	Silver (Ag)	0.00037	0.000605%	7440-22-4
		Nickel (Ni)	0.000159	0.000260%	7440-02-0
	Electrode	Silver (Ag)	0.019	0.0310%	7440-22-4
Crystal	Crystal	Silicon Dioxide (SiO ₂)	1.170	1.91%	14808-60-7
		Ероху	0.0000700	0.0001144%	
	Adhesive	Silver (Ag)	0.000210	0.000343%	7440-22-4
	Gold	Gold (Au)	0.480	0.784%	7440-57-5
		Silicon (Si)	0.950	1.55%	7440-21-3
I C	I C	Aluminum (Al)	0.0021	0.00343%	7429-90-5
		Copper (Cu)	0.210	0.34%	7440-50-8
	+silver solder	Silver (Ag)	1.191	1.95%	7440-22-4
		Cobalt (Co)	0.768	1.25%	7440-48-4
		Nickel (Ni)	1.309	2.14%	7440-02-0
	+Seal ring	Iron (Fe)	2.438	3.98%	7439-89-6
	+ Gold Plating	Gold (Au)	0.281	0.46%	7440-57-5
		Cobalt (Co)	0.203	0.33%	7440-48-4
	+ Nickel Plating	Nickel (Ni)	0.810	1.32%	7440-02-0
		Molybdenum (Mo)	0.195	0.32%	7439-98-7
	+ Metallization	Tungsten (W)	6.290	10.28%	7440-33-7
		Calcium Oxide (CaO)	0.253	0.41%	1305-78-8
		Magnesium Oxide (MgO)	0.234	0.38%	1309-48-4
		Molybdenum Oxide (MoO ₂)	0.364	0.59%	18868-43-4
		Chromium Oxide (Cr ₂ O ₃)	0.268	0.44%	1308-38-9
		Silicon Oxide (SiO ₂)	1.733	2.83%	14808-60-7
Base	Ceramic	Alumina (Al ₂ O ₃)	35.484	57.98%	1344-28-1
		Iron (Fe)	3.540	5.78%	7439-89-6
		Cobalt (Co)	1.113	1.82%	7440-48-4
Cover	Kovar	Nickel (Ni)	1.890	3.09%	7440-02-0
	Triatorial Harrio	Component	(mg)	(w t %)	(CAS Number)
	Material Name	Component	Content	Content	





Datasheet of FXO-HC520-10 - OSC XO 10.000MHZ HCMOS SMD

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FXO-HC52 Series

3rd Party (SGS) Material Report



Test Report No. 2053204/EC Date: Mar 01 2006 Page 1 of 2

FOX ELECTRONICS 5570 ENTERPRISE PARKWAY FT. MYERS, FL 33905

Report on the submitted sample said to be CERAMIC SEAM SEAL OSCILLATOR.

SGS Job No. : 1981176

Supplier / Manufacturer : FOX ELECTRONICS Sample Receiving Date : FEB 17 2006 Testing Period : FEB 18 - 24 2006

Test Requested: 1) To determine the Cadmium Content in the submitted sample.

To determine the Lead Content in the submitted sample.

To determine the Mercury Content in the submitted sample.

4) To determine the Hexavalent Chromium Content on the submitted sample.

 To determine PBBs (polybrominated biphenyls) and PBDEs (Polybrominated diphenylethers) of the submitted sample.

Test Method : 1-3) With reference to EPA Method 3051/3052.

Analysis was performed by Inductively Coupled Argon Plasma-Atomic

Emission Spectrometry (ICP-AES).

With reference to EPA Method 3060A & 7196A.

The sample was alkaline digested by using EPA Method 3060A, and then

analyzed by using Colorimetric method 7196A (by UV-Vis

Spectrophotometer).

With reference to EPA Method 3540C/ 3550C. Analysis was performed by

GC/MS or LC/ MS.

Test Results : 1-5) Please refer to next page.

Signed for and on behalf of SGS Hong Kong Ltd

Ho Ka Ting, Family Laboratory Executive

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SGS Hong Kong Ltd. 5/F - 8/F k. 28/F -29/F, Metropole Square, 2 On Ylu Street, Slu Lek Yuen, Shatin, N.T., Hong Kong. 1 (852) 2334 4481-9 1 (852) 2754 3125 www.hk.sgs.com

Member of the SGS Group (SGS SA)



Datasheet of FXO-HC520-10 - OSC XO 10.000MHZ HCMOS SMD

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FXO-HC52 Series

Material Report (continued) Party (SGS)



Test Report No. 2053204/EC Date: Mar 01 2006 Page 2 of 2

Test Results

Test Item	1	Detection Limit
1) Cadmium (Cd)	ND	2 ppm
2) Lead (Pb)	ND	2 ppm
Mercury (Hg)	ND	2 ppm
4) Hexavalent Chromium (Cr ⁶⁺)	ND	2 ppm

(Results shown are of the total weight of samples)

Note: ppm = mg/kg ND = Not Detected

Not detected is reported when the reading is less than detection limit value

5)

Flame Retardants	1	Detection Limit
Polybrominated Biphenyls (PBBs)		
Monobromobiphenyl	ND	5 ppm
Dibromobiphenyl	ND	5 ppm
Tribromobiphenyl	ND	5 ppm
Tetrabromobiphenyl	ND	5 ppm
Pentabromobiphenyl	ND	5 ppm
Hexabromobiphenyl	ND	5 ppm
Heptabromobiphenyl	ND	5 ppm
Octabromobiphenyl	ND	5 ppm
Nonabromobiphenyl	ND	5 ppm
Decabromobiphenyl	ND	5 ppm
Polybrominated Diphenylethers (PBDEs)		
Monobromodiphenyl ether	ND	5 ppm
Dibromodiphenyl ether	ND	5 ppm
Tribromodiphenyl ether	ND	5 ppm
Tetrabromodiphenyl ether	ND	5 ppm
Pentabromodiphenyl ether	ND	5 ppm
Hexabromodiphenyl ether	ND	5 ppm
Heptabromodiphenyl ether	ND	5 ppm
Octabromodiphenyl ether	ND	5 ppm
Nonabromodiphenyl ether	ND	5 ppm
Decabromodiphenyl ether	ND	5 ppm

Note ppm = mg/kg

ND = Not Detected

Not detected is reported when the reading is less than detection limit value.

Sample Description:

Black Ceramic w/ Silvery, Golden Metal w/ Silvery Chips

*** End of Report ***

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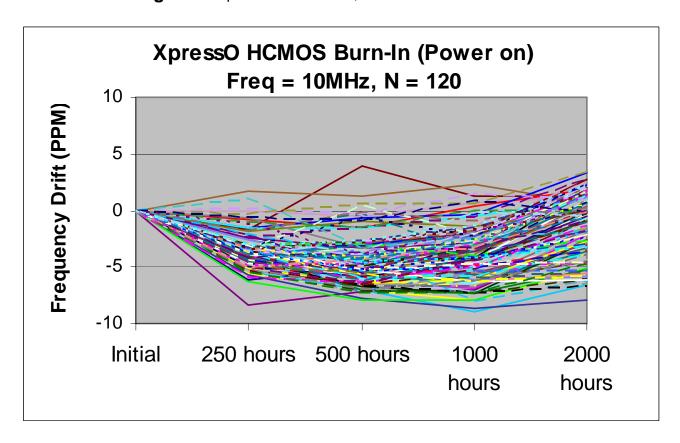


Mechanical Testing

Parameter	Test Method
Mechanical Shock	Drop from 75cm to hardwood surface – 3 times
Mechanical Vibration	10~55Hz, 1.5mm amplitude, 1 Minute Sweep 2 Hours each in 3 Directions (X, Y, Z)
High Temperature Burn-in	Under Power @ 125°C for 2000 Hours (results below)
Hermetic Seal	He pressure: 4 ±1 kgf / cm ² 2 Hour soak

2,000 Hour Burn-In

Burn-In Testing – under power 2000 Hours, 125°C









MTTF / FITS Calculations

Products are grouped together by process for MTTF calculations. (All XpressO output and package types are manufactured with the same process)

Number of Parts Tested: 360 (120 of each output type: HCMOS, LVDS, LVPECL)

Number of Failures: 0 Test Temperature: 125°C Number of Hours: 2000

MTTF was calculated using the following formulas:

[1.] Device Hours (devhrs) = (number of devices) x (hours at elevated temperature in °K)

[2.]
$$MTTF = \frac{devhrs \times af \times 2}{\chi^2}$$

[3.] FITS =
$$\frac{1}{MTTF}$$
 * 10⁹

Where:

Label	Name	Formula/Value
af	Acceleration Factor	$e^{(rac{eV}{k}) imes(rac{1}{t_1}-rac{1}{t_2})}$
eV	Activation Energy	0.40 V
k	Bolzman's Constant	8.62 X 10 ⁻⁵ eV/°K
t ₁		Operating Temperature (°K)
t ₂		Accelerated Temperature (°K)
Θ	Theta	Confidence Level (60% industry standard)
r	Failures	Number of failed devices
χ²	Chi-Square	statistical significance for bivariate tabular analysis [table look-up] based on assumed Θ (Theta – confidence) and number of failures (r) For zero failures (60% Confidence): $\chi^2 = 1.830$

DEVICE-HOURS = 360 x 2000 HOURS = 720,000

ACCELERATION FACTOR =
$$e^{(\frac{0.40}{8.625})\times(\frac{1}{298}-\frac{1}{398})}$$
 = 49.91009

MTTF =
$$\frac{720,000 \times 49.91009 \times 2}{1.833}$$
 = 39,209,238 Hours

Failure Rate =
$$\frac{1.833}{720,000 \times 49.91009 \times 2}$$
 = 2.55E-8

FITS = Failure Rate *1E9 = 26





Datasheet of FXO-HC520-10 - OSC XO 10.000MHZ HCMOS SMD

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FXO-HC52 Series

Notes:

For the complete product line of XPRESSO products visit

http://www.foxonline.com/xpressomain.htm

Patent Numbers:

US 6,664,860, US 5,960,403, US 5,952,890; US 5,960,405; US 6,188,290;
Foreign Patents: R.S.A. 98/0866, R.O.C. 120851; Singapore 67081, 67082; EP 0958652
China ZL 98802217.6, Malaysia MY-118540-A, Philippines 1-1998-000245, Hong Kong #HK1026079, Mexico #232179
US and Foreign Patents Pending

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The above specifications, having been carefully prepared and checked, is believed to be accurate at the time of publication; however, no responsibility is assumed by Fox Electronics for inaccuracies.

